

EMI SHIELDED INTEGRATED CIRCUIT PACKAGING APPARATUS METHOD AND SYSTEM

ABSTRACT OF THE DISCLOSURE

A package shell that is electrically and thermally conductive is placed over an integrated circuit die and associated wire-bond connections to electromagnetically shield the resulting integrated circuit package. The package shell is attached to the top surface of a substrate bearing the integrated circuit die and is electrically connected to a grounding path. The package shell may be filled with a thermally conductive filler in order to increase the heat dissipation and EMI shielding of the resulting integrated circuit package.